

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPI120N06S4-02	**Issued**	04. May 2021
MA#	MA001055194		
Package	PG-TO262-3-1	**Weight***	1577.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.633	0.48	0.48	4837	4837
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		162	
	non noble metal	iron	7439-89-6	0.851	0.05		539	
	non noble metal	copper	7440-50-8	849.682	53.86	53.93	538459	539160
wire	non noble metal	aluminium	7429-90-5	11.551	0.73	0.73	7320	7320
encapsulation	inorganic material	zincoxide	1314-13-2	5.809	0.37		3681	
	miscellaneous	miscellaneous	-	23.237	1.47		14726	
	plastics	epoxy resin	-	87.138	5.52		55221	
	inorganic material	silicondioxide	60676-86-0	464.734	29.45	36.81	294511	368139
leadfinish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9631	9631
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.106	0.01		67	
	noble metal	silver	7440-22-4	0.133	0.01		84	
	non noble metal	lead	7439-92-1	5.085	0.32	0.34	3222	3373
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			20	
	non noble metal	iron	7439-89-6	0.106	0.01		67	
	non noble metal	copper	7440-50-8	106.210	6.73	6.74	67307	67394
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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